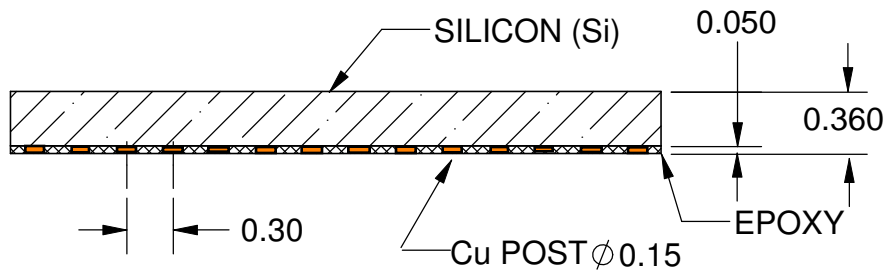
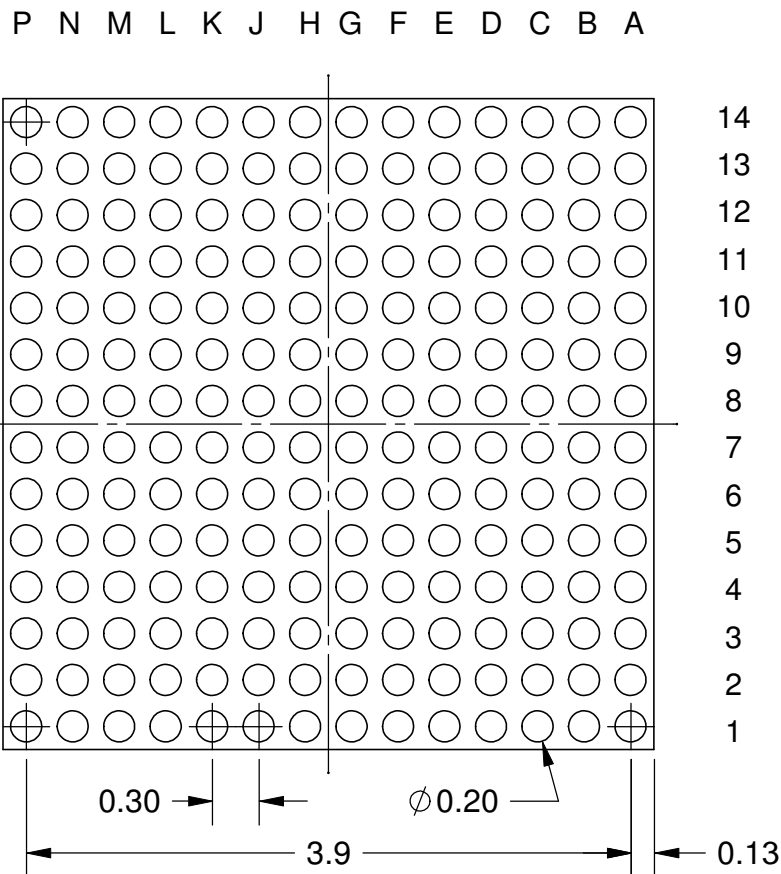
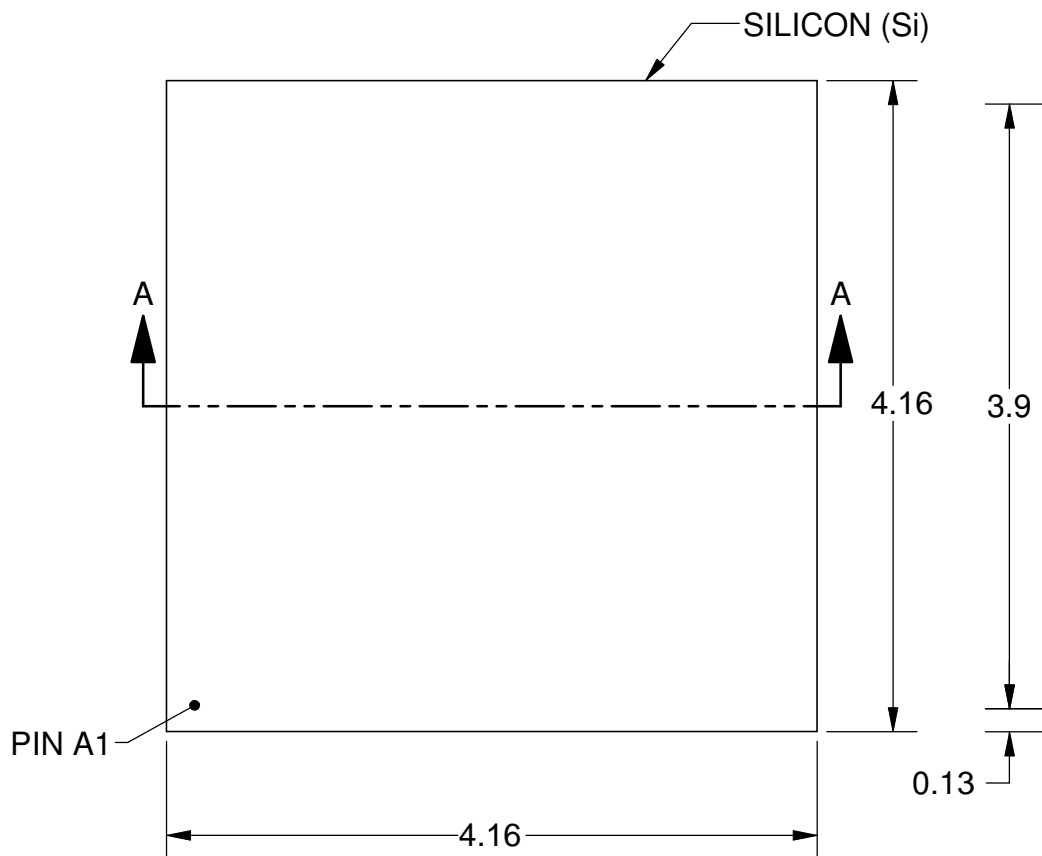


TOP VIEW


PAD VIEW



Notes: (Unless Otherwise Specified).
 1) ALL DIMENSIONS ARE IN MM.
 2) PAD ALLOY: Cu (50um Thick)

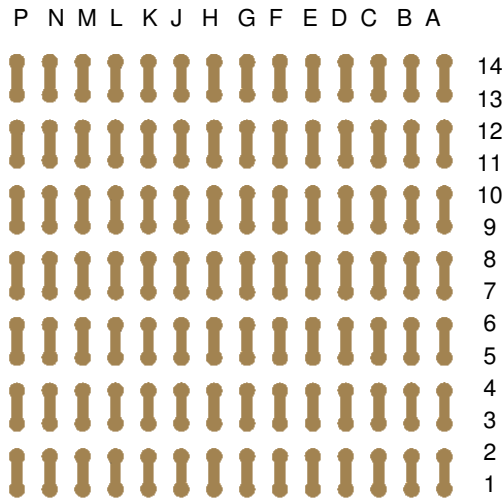
3) PAD Cu DIAMETER: 0.15mm.
 4) DIE MATERIAL: Si (SILICON).
 5) DAISY CHAIN PATTERN (SEE PAGE 2).

SECTION A-A

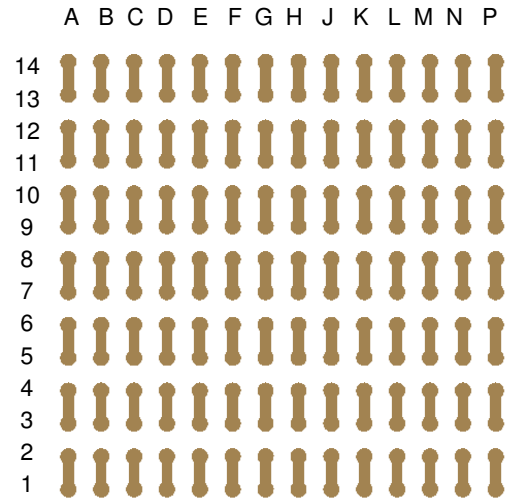
TOLERANCE UNLESS NOTED		APPROVALS		DATE				
X.X	+/- 0.3	DRAWN J. Hines		12/29/2010				
X.XX	+/- 0.03							
X.XXX	+/- 0.003	MFG		QA	SCALE 20.5:1	SIZE A	DRAWING NO. 731480	REV A
ANGLES +/- 0.5° ALL DIMENSIONS IN <input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS THIRD ANGLE PROJECTION								
		REVISED						

DAISY CHAIN PATTERN

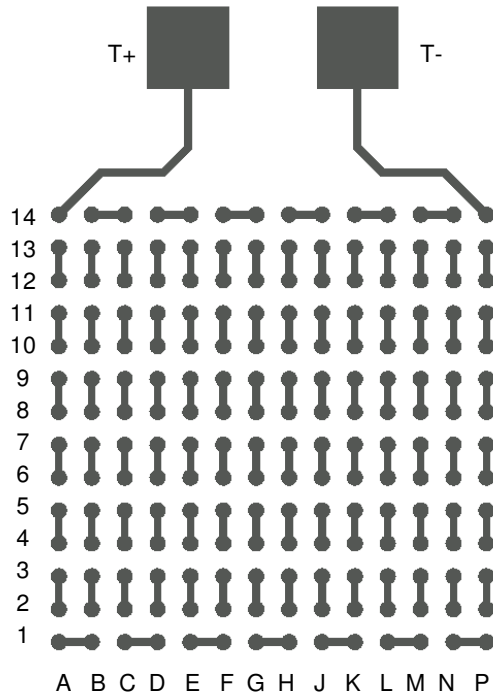
PAD VIEW



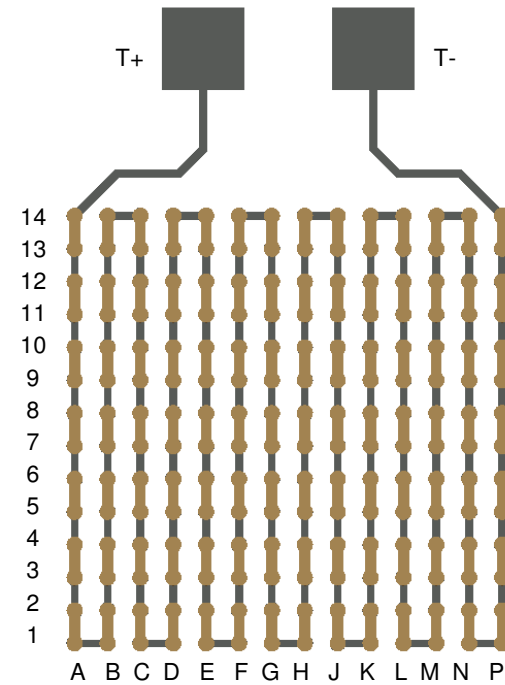
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

TopLine ®			
TITLE eWLP196T.3-DC148D3 196-L P=0.3mm (TEG0306)			
SCALE 14.5:1	SIZE A	DRAWING NO. 731480	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	